

## 74LCX125

### Low Voltage Quad Buffer with 5V Tolerant Inputs and Outputs

#### General Description

The LCX125 contains four independent non-inverting buffers with 3-STATE outputs. The inputs tolerate voltages up to 7V allowing the interface of 5V systems to 3V systems. The 74LCX125 is fabricated with an advanced CMOS technology to achieve high speed operation while maintaining CMOS low power dissipation.

#### Features

- 5V tolerant inputs and outputs
- 2.3V–3.6V  $V_{CC}$  specifications provided
- 6.0 ns  $t_{PD}$  max ( $V_{CC} = 3.3V$ ), 10  $\mu A$   $I_{CC}$  max
- Power down high impedance inputs and outputs
- Supports live insertion/withdrawal (Note 1)
- $\pm 24$  mA output drive ( $V_{CC} = 3.0V$ )
- Implements patented noise/EMI reduction circuitry
- Latch-up performance exceeds JEDEC 78 conditions
- ESD performance:
  - Human body model > 2000V
  - Machine model > 100V
- Leadless Pb-Free DQFN package

**Note 1:** To ensure the high-impedance state during power up or down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pull-up resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

#### Ordering Code:

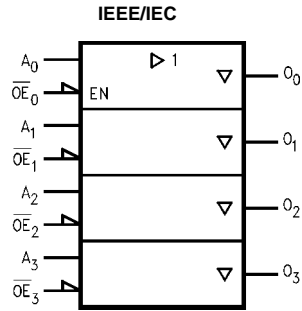
Order Number	Package Number	Package Description
74LCX125M	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
74LCX125MX_NL (Note 3)	M14A	Pb-Free 14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
74LCX125SJ	M14D	Pb-Free 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74LCX125BQX (Note 2)	MLP014A	Pb-Free 14-Terminal Depopulated Quad Very-Thin Flat Pack No Leads (DQFN), JEDEC MO-241, 2.5 x 3.0mm
74LCX125MTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
74LCX125MTCX_NL (Note 3)	MTC14	Pb-Free 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering code.  
Pb-Free package per JEDEC J-STD-020B.

**Note 2:** DQFN package available in Tape and Reel only.

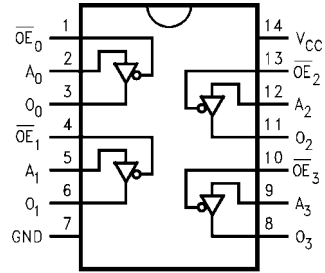
**Note 3:** "\_NL" indicates Pb-Free package (per JEDEC J-STD-020B). Device available in Tape and Reel only.

**Logic Symbol**



**Connection Diagrams**

Pin Assignments for SOIC, SOP, and TSSOP



**Pin Descriptions**

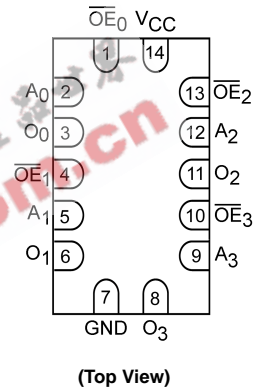
Pin Names	Description
$A_n$	Inputs
$\overline{OE}_n$	Output Enable Inputs
$O_n$	Outputs

**Truth Table**

Inputs		Output
$\overline{OE}_n$	$A_n$	$O_n$
L	L	L
L	H	H
H	X	Z

H = HIGH Voltage Level  
 L = LOW Voltage Level  
 Z = High Impedance  
 X = Immaterial

Pad Assignments for DQFN



Absolute Maximum Ratings (Note 4)				
Symbol	Parameter	Value	Conditions	Units
$V_{CC}$	Supply Voltage	-0.5 to +7.0		V
$V_I$	DC Input Voltage	-0.5 to +7.0		V
$V_O$	DC Output Voltage	-0.5 to +7.0	Output in 3-STATE	V
		-0.5 to $V_{CC} + 0.5$	Output in HIGH or LOW State (Note 5)	V
$I_{IK}$	DC Input Diode Current	-50	$V_I < GND$	mA
$I_{OK}$	DC Output Diode Current	-50	$V_O < GND$	mA
		+50	$V_O > V_{CC}$	mA
$I_O$	DC Output Source/Sink Current	$\pm 50$		mA
$I_{CC}$	DC Supply Current per Supply Pin	$\pm 100$		mA
$I_{GND}$	DC Ground Current per Ground Pin	$\pm 100$		mA
$T_{STG}$	Storage Temperature	-65 to +150		$^{\circ}C$

Recommended Operating Conditions (Note 6)					
Symbol	Parameter	Min	Max	Units	
$V_{CC}$	Supply Voltage	Operating	2.0	3.6	V
		Data Retention	1.5	3.6	V
$V_I$	Input Voltage	0	5.5	V	
$V_O$	Output Voltage	HIGH or LOW State	0	$V_{CC}$	V
		3-STATE	0	5.5	V
$I_{OH}/I_{OL}$	Output Current	$V_{CC} = 3.0V - 3.6V$		$\pm 24.0$	mA
		$V_{CC} = 2.7V - 3.0V$		$\pm 12.0$	
		$V_{CC} = 2.3V - 2.7V$		$\pm 8.0$	
$T_A$	Free-Air Operating Temperature	-40.0	85.0	$^{\circ}C$	
$\Delta t/\Delta V$	Input Edge Rate, $V_{IN} = 0.8V - 2.0V$ , $V_{CC} = 3.0V$	0	10.0	ns/V	

**Note 4:** The Absolute Maximum Ratings are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the Absolute Maximum Ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

**Note 5:**  $I_O$  Absolute Maximum Rating must be observed.

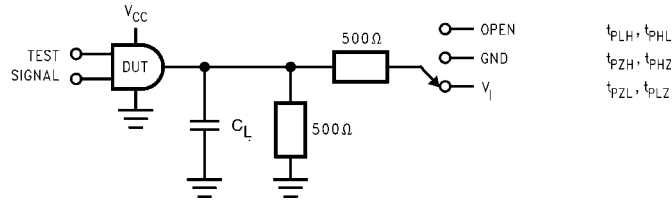
**Note 6:** Unused inputs or I/Os must be held HIGH or LOW. They may not float.

## DC Electrical Characteristics

Symbol	Parameter	Conditions	$V_{CC}$ (V)	$T_A = -40^{\circ}C$ to $+85^{\circ}C$		Units
				Min	Max	
$V_{IH}$	HIGH Level Input Voltage		2.3-2.7	1.7		V
			2.7-3.6	2.0		
$V_{IL}$	LOW Level Input Voltage		2.3-2.7		0.7	V
			2.7-3.6		0.8	
$V_{OH}$	HIGH Level Output Voltage	$I_{OH} = -100 \mu A$	2.3-3.6	$V_{CC} - 0.2$		V
		$I_{OH} = -8 \text{ mA}$	2.3	1.8		
		$I_{OH} = -12 \text{ mA}$	2.7	2.2		
		$I_{OH} = -18 \text{ mA}$	3.0	2.4		
		$I_{OH} = -24 \text{ mA}$	3.0	2.2		
$V_{OL}$	LOW Level Output Voltage	$I_{OL} = 100 \mu A$	2.3-3.6		0.2	V
		$I_{OL} = 8 \text{ mA}$	2.3		0.6	
		$I_{OL} = 12 \text{ mA}$	2.7		0.4	
		$I_{OL} = 16 \text{ mA}$	3.0		0.4	
		$I_{OL} = 24 \text{ mA}$	3.0		0.55	
$I_I$	Input Leakage Current	$0 \leq V_I \leq 5.5V$	2.3-3.6		$\pm 5.0$	$\mu A$
$I_{OZ}$	3-STATE Output Leakage	$0 \leq V_O \leq 5.5V$ $V_I = V_{IH}$ or $V_{IL}$	2.3-3.6		$\pm 5.0$	$\mu A$
$I_{OFF}$	Power-Off Leakage Current	$V_I$ or $V_O = 5.5V$	0		10.0	$\mu A$

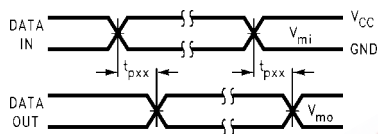
DC Electrical Characteristics (Continued)								
Symbol	Parameter	Conditions	V <sub>CC</sub> (V)	T <sub>A</sub> = -40°C to +85°C		Units		
				Min	Max			
I <sub>CC</sub>	Quiescent Supply Current	V <sub>I</sub> = V <sub>CC</sub> or GND	2.3 – 3.6		10.0	μA		
		3.6V ≤ V <sub>I</sub> , V <sub>O</sub> ≤ 5.5V (Note 7)	2.3 – 3.6		±10.0			
ΔI <sub>CC</sub>	Increase in I <sub>CC</sub> per Input	V <sub>IH</sub> = V <sub>CC</sub> - 0.6V	2.3 – 3.6		500	μA		
<b>Note 7:</b> Outputs disabled or 3-STATE only.								
AC Electrical Characteristics								
Symbol	Parameter	T <sub>A</sub> = -40°C to +85°C, R <sub>L</sub> = 500Ω						Units
		V <sub>CC</sub> = 3.3V ± 0.3V		V <sub>CC</sub> = 2.7V		V <sub>CC</sub> = 2.5V ± 0.2V		
		C <sub>L</sub> = 50 pF		C <sub>L</sub> = 50 pF		C <sub>L</sub> = 30 pF		
		Min	Max	Min	Max	Min	Max	
t <sub>PHL</sub>	Propagation Delay	1.5	6.0	1.5	6.5	1.5	7.2	ns
t <sub>PLH</sub>		1.5	6.0	1.5	6.5	1.5	7.2	
t <sub>PZL</sub>	Output Enable Time	1.5	7.0	1.5	8.0	1.5	9.1	ns
t <sub>PZH</sub>		1.5	7.0	1.5	8.0	1.5	9.1	
t <sub>PLZ</sub>	Output Disable Time	1.5	6.0	1.5	7.0	1.5	7.2	ns
t <sub>PHZ</sub>		1.5	6.0	1.5	7.0	1.5	7.2	
t <sub>OSSL</sub>	Output to Output Skew (Note 8)		1.0					ns
t <sub>OSLH</sub>			1.0					
<b>Note 8:</b> Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t <sub>OSSL</sub> ) or LOW-to-HIGH (t <sub>OSLH</sub> ).								
Dynamic Switching Characteristics								
Symbol	Parameter	Conditions	V <sub>CC</sub> (V)	T <sub>A</sub> = 25°C		Units		
				Typical				
V <sub>OLP</sub>	Quiet Output Dynamic Peak V <sub>OL</sub>	C <sub>L</sub> = 50 pF, V <sub>IH</sub> = 3.3V, V <sub>IL</sub> = 0V C <sub>L</sub> = 30 pF, V <sub>IH</sub> = 2.5V, V <sub>IL</sub> = 0V	3.3 2.5	0.8 0.6		V		
V <sub>OLV</sub>	Quiet Output Dynamic Valley V <sub>OL</sub>	C <sub>L</sub> = 50 pF, V <sub>IH</sub> = 3.3V, V <sub>IL</sub> = 0V C <sub>L</sub> = 30 pF, V <sub>IH</sub> = 2.5V, V <sub>IL</sub> = 0V	3.3 2.5	-0.8 -0.6				
Capacitance								
Symbol	Parameter	Conditions	Typical	Units				
C <sub>IN</sub>	Input Capacitance	V <sub>CC</sub> = Open, V <sub>I</sub> = 0V or V <sub>CC</sub>	7.0	pF				
C <sub>OUT</sub>	Output Capacitance	V <sub>CC</sub> = 3.3V, V <sub>I</sub> = 0V or V <sub>CC</sub>	8.0	pF				
C <sub>PD</sub>	Power Dissipation Capacitance	V <sub>CC</sub> = 3.3V, V <sub>I</sub> = 0V or V <sub>CC</sub> , f = 10 MHz	25.0	pF				

**AC Loading and Waveforms** Generic for LCX Family

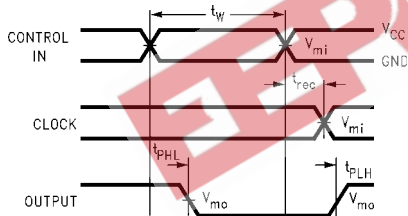


**FIGURE 1. AC Test Circuit**  
( $C_L$  includes probe and jig capacitance)

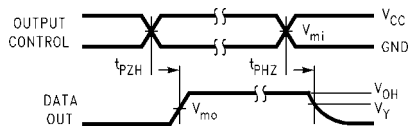
Test	Switch
$t_{PLH}, t_{PHL}$	Open
$t_{PZL}, t_{PLZ}$	6V at $V_{CC} = 3.3 \pm 0.3V$ $V_{CC} \times 2$ at $V_{CC} = 2.5 \pm 0.2V$
$t_{PZH}, t_{PHZ}$	GND



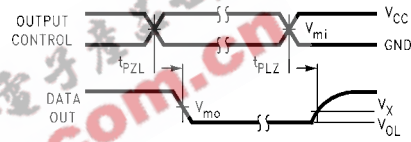
**Waveform for Inverting and Non-Inverting Functions**



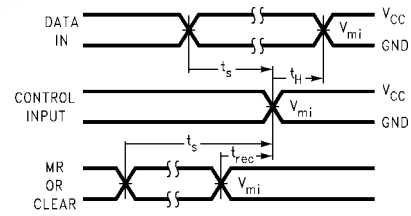
**Propagation Delay, Pulse Width and  $t_{rec}$  Waveforms**



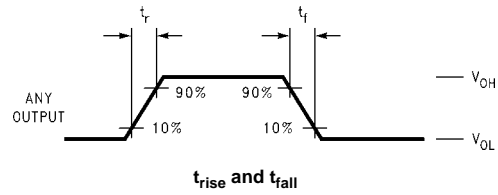
**3-STATE Output High Enable and Disable Times for Logic**



**3-STATE Output Low Enable and Disable Times for Logic**

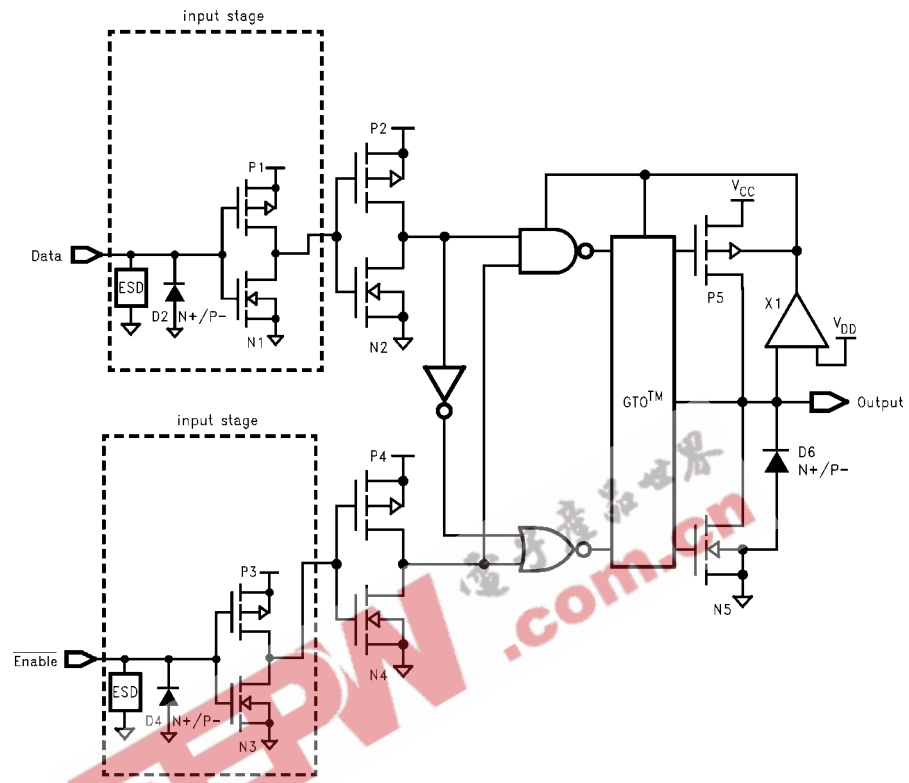


**Setup Time, Hold Time and Recovery Time for Logic**



**FIGURE 2. Waveforms**  
(Input Pulse Characteristics;  $f = 1\text{MHz}$ ,  $t_r = t_f = 3\text{ns}$ )

Symbol	$V_{CC}$		
	$3.3V \pm 0.3V$	$2.7V$	$2.5V \pm 0.2V$
$V_{mi}$	1.5V	1.5V	$V_{CC}/2$
$V_{mo}$	1.5V	1.5V	$V_{CC}/2$
$V_x$	$V_{OL} + 0.3V$	$V_{OL} + 0.3V$	$V_{OL} + 0.15V$
$V_y$	$V_{OH} - 0.3V$	$V_{OH} - 0.3V$	$V_{OH} - 0.15V$

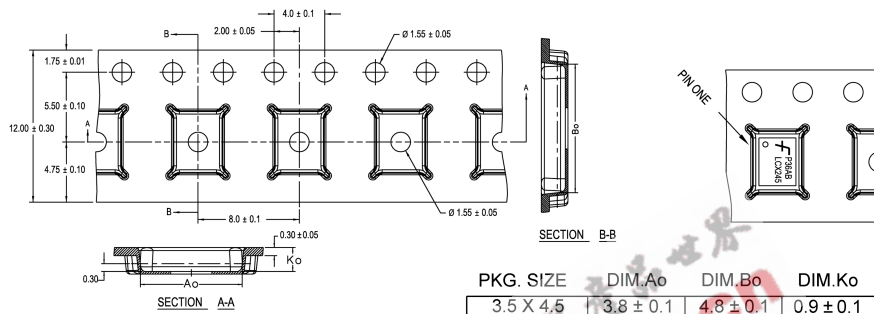
**Schematic Diagram** Generic for LCX Family

### Tape and Reel Specification

**Tape Format for DQFN**

Package Designator	Tape Section	Number Cavities	Cavity Status	Cover Tape Status
BQX	Leader (Start End)	125 (typ)	Empty	Sealed
	Carrier	2500/3000	Filled	Sealed
	Trailer (Hub End)	75 (typ)	Empty	Sealed

**TAPE DIMENSIONS** inches (millimeters)



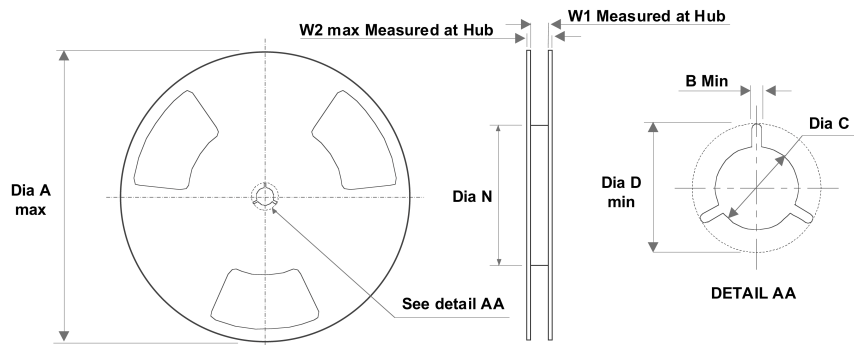
PKG. SIZE	DIM.Ao	DIM.Bo	DIM.Ko
3.5 X 4.5	3.8 ± 0.1	4.8 ± 0.1	0.9 ± 0.1
3.0 X 3.0	3.3 ± 0.1	3.3 ± 0.1	0.9 ± 0.1
2.5 X 4.5	2.8 ± 0.1	4.8 ± 0.1	0.9 ± 0.1
2.5 X 3.5	2.8 ± 0.1	3.8 ± 0.1	0.9 ± 0.1
2.5 X 3.0	2.8 ± 0.1	3.3 ± 0.1	0.9 ± 0.1
2.5 X 2.5	2.8 ± 0.1	2.8 ± 0.1	0.9 ± 0.1

DIMENSIONS ARE IN MILLIMETERS

NOTES: unless otherwise specified

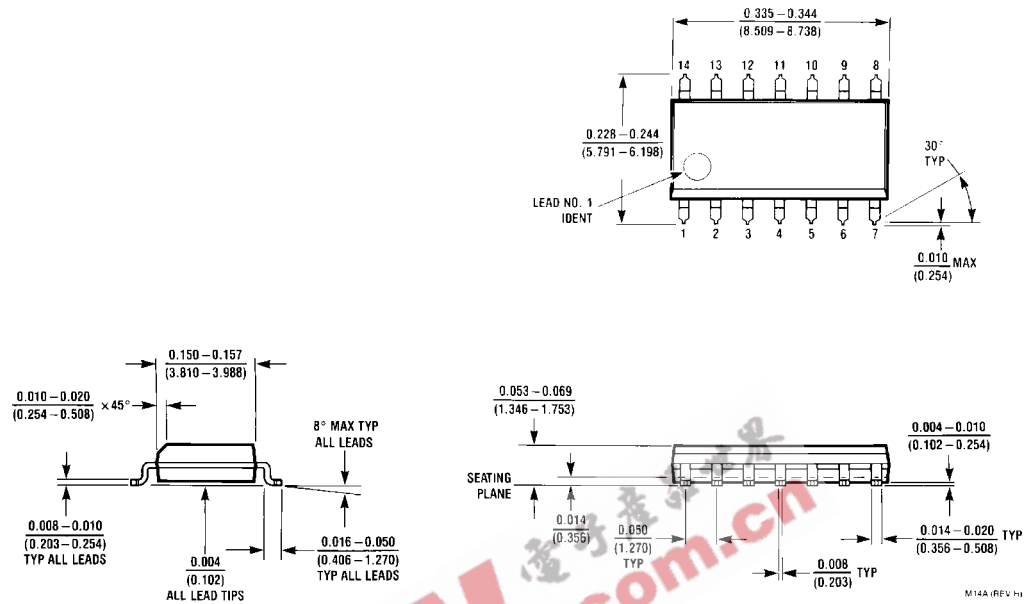
- Cumulative pitch for feeding holes and cavities (chip pockets) not to exceed 0.008[0.20] over 10 pitch span.
- Smallest allowable bending radius.
- Thru hole inside cavity is centered within cavity.
- Tolerance is ±0.002[0.05] for these dimensions on all 12mm tapes.
- Ao and Bo measured on a plane 0.120[0.30] above the bottom of the pocket.
- Ko measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
- Pocket position relative to sprocket hole measured as true position of pocket. Not pocket hole.
- Controlling dimension is millimeter. Dimension in inches rounded.

**REEL DIMENSIONS** inches (millimeters)



Tape Size	A	B	C	D	N	W1	W2
12 mm	13.0 (330)	0.059 (1.50)	0.512 (13.00)	0.795 (20.20)	7.008 (178)	0.488 (12.4)	0.724 (18.4)

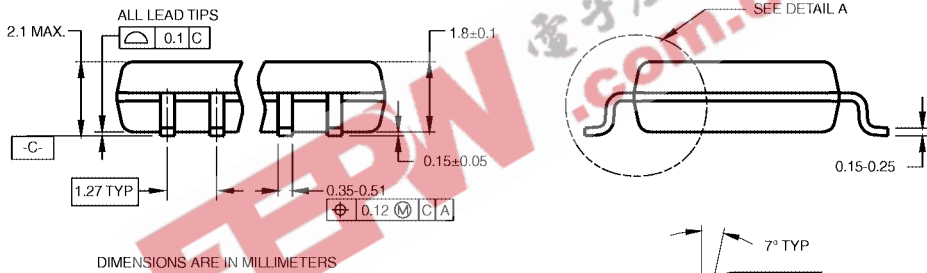
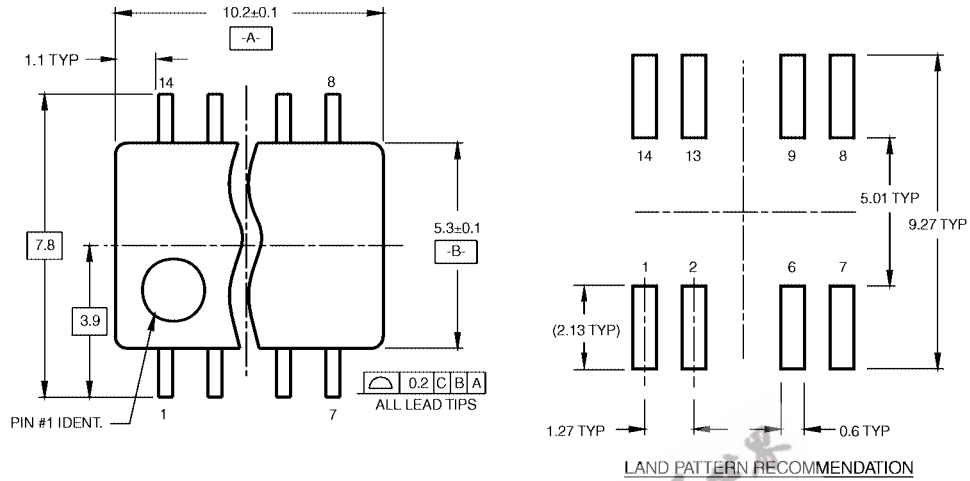
**Physical Dimensions** inches (millimeters) unless otherwise noted



14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow  
Package Number M14A



**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)

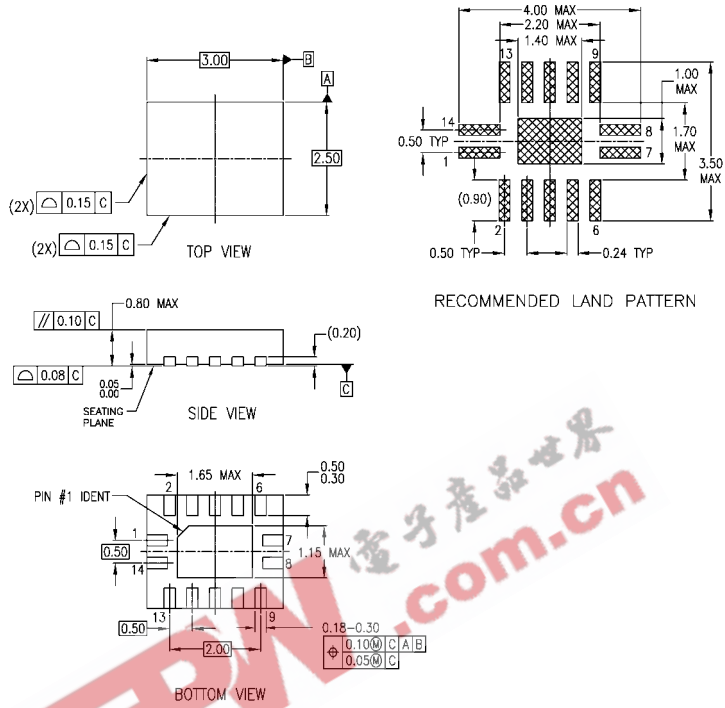


- NOTES:  
 A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.  
 B. DIMENSIONS ARE IN MILLIMETERS.  
 C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M14DRevB1

**Pb-Free 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide  
 Package Number M14D**

**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)

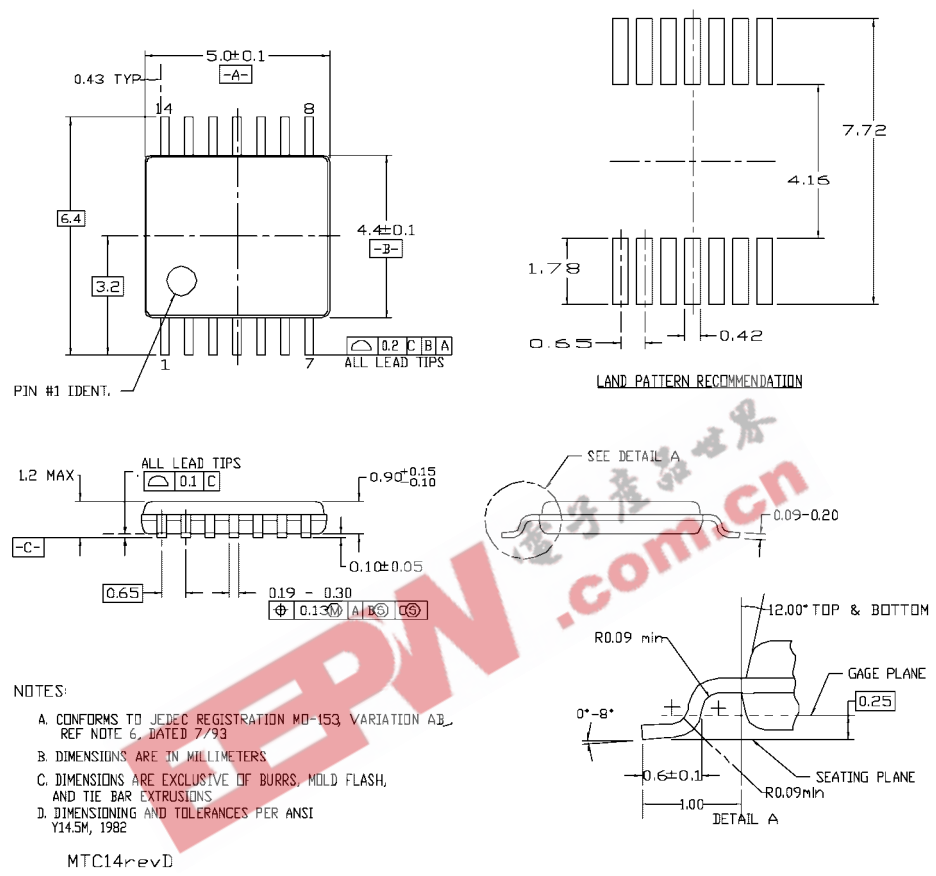


- NOTES:
- A. CONFORMS TO JEDEC REGISTRATION MO-241, VARIATION AA
  - B. DIMENSIONS ARE IN MILLIMETERS.
  - C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994

MLP014ArevA

**Pb-Free 14-Terminal Depopulated Quad Very-Thin Flat Pack No Leads (DQFN), JEDEC MO-241, 2.5 x 3.0mm Package Number MLP014A**

**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)



- NOTES:
- A. CONFORMS TO JEDEC REGISTRATION MO-153 VARIATION AB, REF NOTE 6, DATED 7/93
  - B. DIMENSIONS ARE IN MILLIMETERS
  - C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
  - D. DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 1982
- MTC14revD

**14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC14**

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2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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